

Balanced Technology Extended (BTX) Interface Specification

Version 1.0

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Revision History

| Version | Description | Date |
|----------------|--------------------|----------------|
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1. Introduction

The Balanced Technology Extended (BTX) interface specification was developed to provide standard interfaces and form factor definitions to address the electrical, thermal, and mechanical attributes of desktop computer systems. The specification is intended to allow for a wide variety of product differentiation that can be adapted to multiple applications and usage models.

This specification describes the critical mechanical and electrical interfaces for the design of chassis, motherboard, power supply, and other system components necessary for hardware vendors and integrators to build and integrate compliant components, systems, and devices that are interoperable with each other. The intention of this document is not to provide all requirements necessary to design any one of these components, but instead to provide standard interfaces for the components to be designed around.

Table 1 summarizes some of the key features enabled by the BTX specification.

Table 1. BTX Feature Summary

| Features | Benefits |
|-------------------------------------|--|
| Low profile options | Easy integration in small, thin form factor systems |
| In-line core layout | Optimized for efficient system cooling |
| Scaleable board dimensions | Multiple system sizes and configurations |
| Structural board support mechanisms | Mechanical characteristics to support high-mass motherboard components |

Table 2 details the interfaces defined in this specification and the section(s) that address each.

Table 2. Specification Quick Reference

| Interfaces | Features Defining Interface | Related Section(s) |
|--|---|---------------------------------|
| Board/Chassis Interfaces | Motherboard geometry and mounting hole locations (mechanical) | Section 3.1 |
| | Motherboard volumetric zones (mechanical) | Section 3.2 |
| | Chassis volumetric zones (mechanical) | Section 3.2.2 |
| | Rear panel chassis I/O locations and openings (mechanical) | Section 3.3.4 and Section 3.4.1 |
| Board/Power Supply Interfaces | Main power connector (electrical and mechanical) | Section 4 |
| | +12V power connector (electrical and mechanical) | Section 4 |
| Chassis interfaces to other components | Chassis interface to SRM (mechanical) | Section 3.3.2 |
| | Chassis interface to Thermal Module (mechanical) | Section 3.3.3 |

1.1 Terminology

Table 3 explains terms introduced in this specification.

Table 3. Terminology

| Term | Definition |
|------------------------------------|---|
| Support and Retention Module (SRM) | System component that is assembled to the chassis beneath the motherboard to provide structural support for motherboard and components as well as retention for a thermal module. |
| Thermal Module | A system component with the primary role of dissipating heat from the core components. A typical thermal module includes a heatsink for the processor, an air mover such as an axial fan, and a duct to isolate and direct airflow through the system. The flexibility to adapt to many applications is offered through the option to integrate a range of cooling technologies and components to create a thermal module. Modules will be one of two types based on which Zone A component height maximum (see Figure 4, page 15) is selected: Type I (Standard Height) or Type II (Low Profile). |

1.2 Related Documents

Table 4 lists documents related to this specification.

Table 4. Related Documents

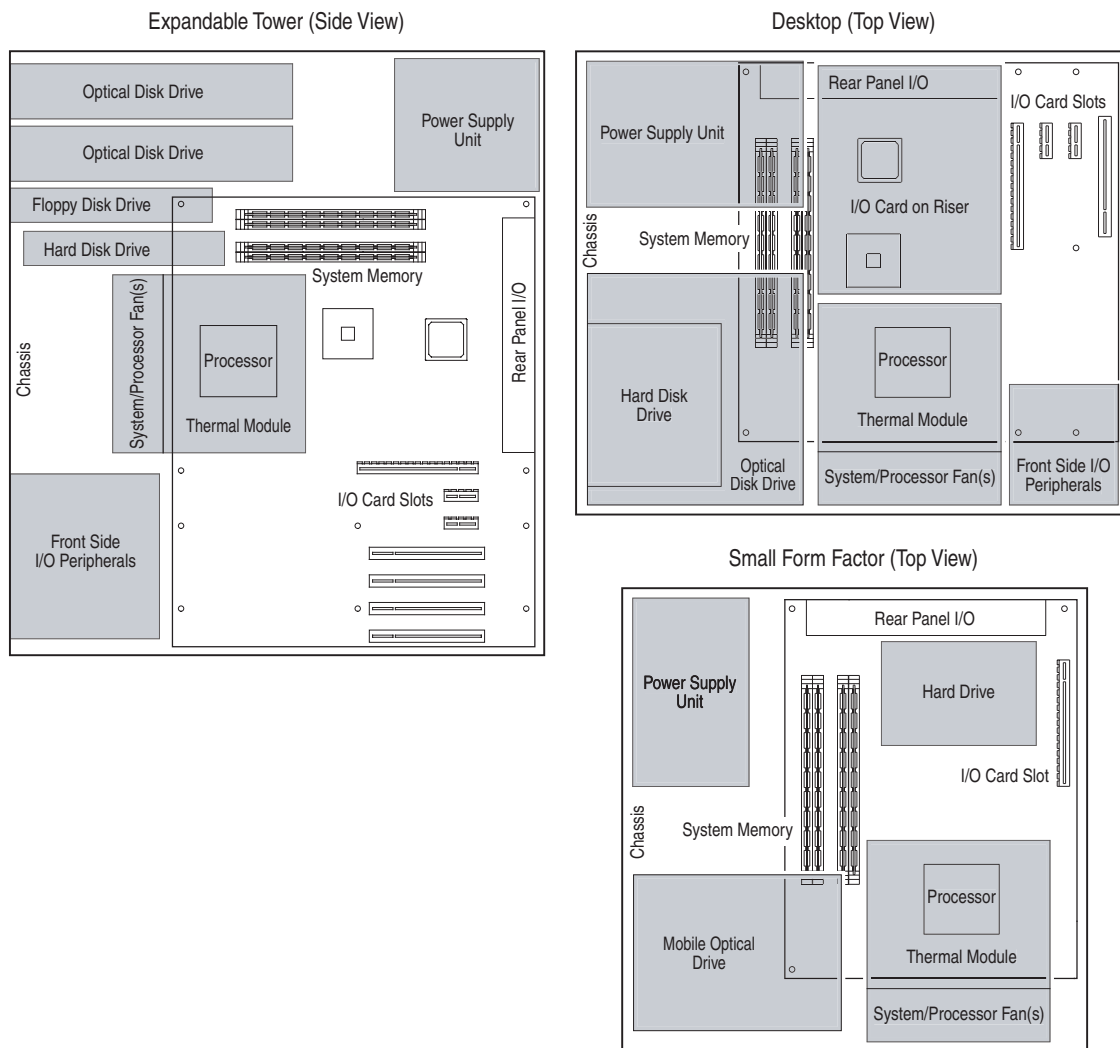
| Specification | Location |
|---------------------------------|---|
| PCI Express* Specifications | http://www.pcisig.com/specifications/pciexpress/ |
| Conventional PCI Specifications | http://www.pcisig.com/specifications/conventional/ |
| ATX and microATX Specifications | http://www.formfactors.org |

2. Form Factor Overview

This specification allows the processor, chipset, memory, add-in cards, and other components to be designed and located in a way that facilitates both efficient motherboard routing and cooling of the components. It also allows options for system layouts that can accommodate a range of profiles and sizes – from compact systems and devices to large, very expandable systems.

The power supply connectors and interfaces are defined to be compatible with those defined for the ATX family of form factors. For more information on standard power supply definitions and the ATX form factor family, see the references listed in Chapter 5.

Figure 1 shows three examples of the many layouts possible with the BTX form factor.



Note: Illustrations not to scale

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Figure 1. Example BTX Board and System Layouts

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3. Mechanical Requirements

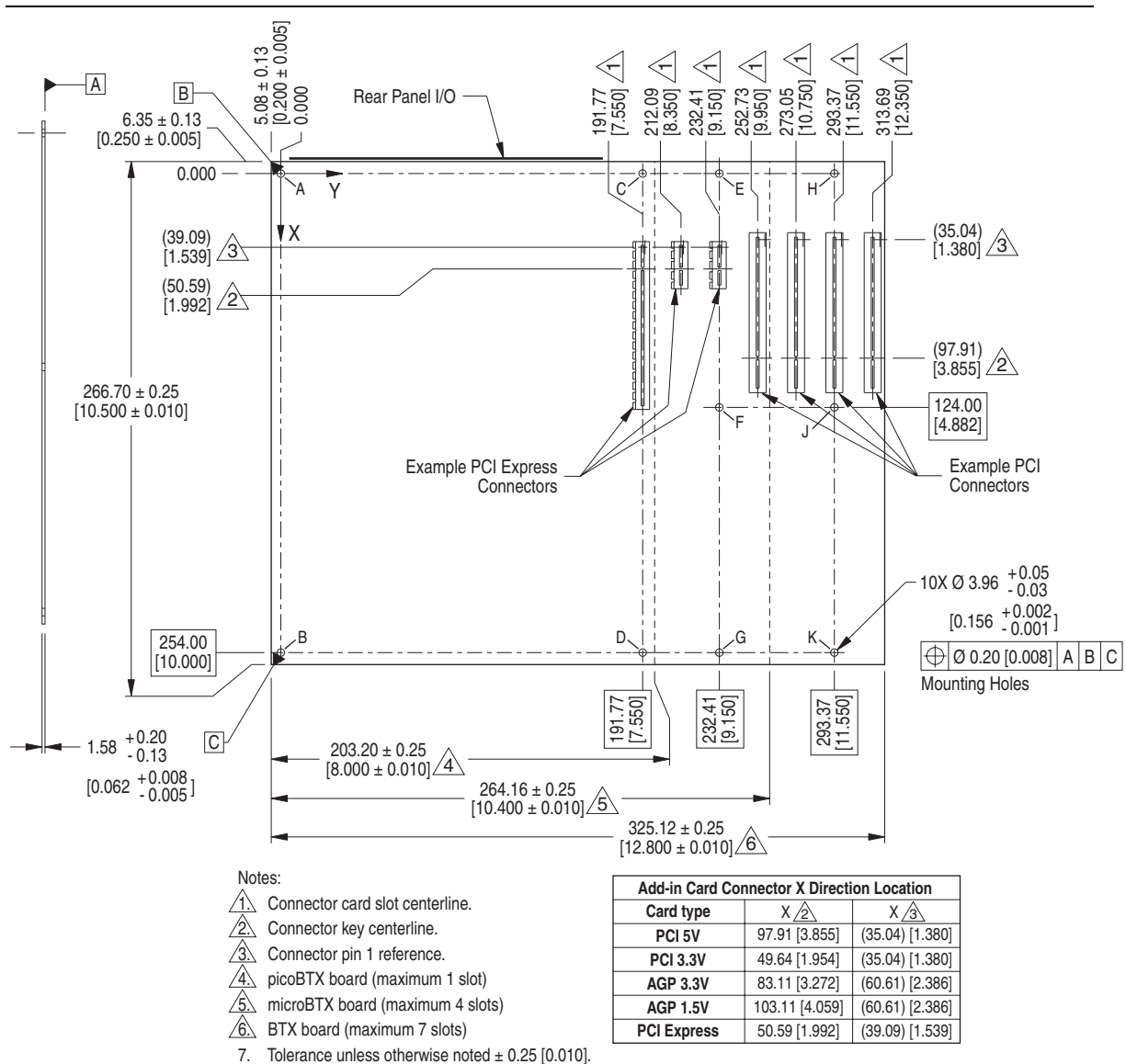
This chapter describes the mechanical requirements of BTX system components and the associated interfaces.

3.1 Motherboard Size and Mounting Hole Placement

A BTX board must adhere to the mechanical details depicted in Figure 2. All boards must be 266.70 mm deep. The board width may range from 203.20 mm to 325.12 mm per Table 5. Table 2 lists example board sizes and the mounting holes required for the motherboard. A BTX chassis should provide mounting points and add-in card apertures in the rear panel for the largest board that it is intended to support.

Table 5. Board Size Options

| Board Designation | Maximum Nominal Board Width | Typical Number of Add-in Card Slots Available | Required Mounting Hole Locations | Notes |
|--------------------------|------------------------------------|--|---|--------------|
| picoBTX | 203.20 mm | 1 | A, B, C, D | |
| microBTX | 264.16 mm | 4 | A, B, C, D, E, F, G | |
| BTX | 325.12 mm | 7 | A, B, C, D, E, F, G, H, J, K | |



OM16309

Figure 2. BTX Form Factor Board and Mounting Hole Dimensions

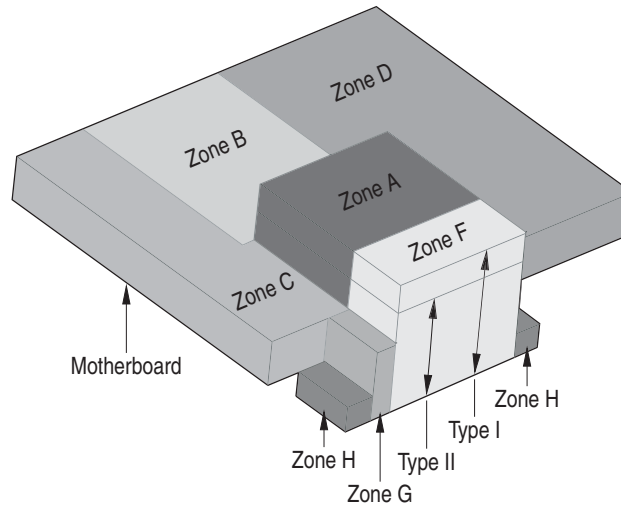
3.2 Volumetric Zones

Volumetric zones are defined to provide a definition for mechanical requirements for each of the key system components areas. These definitions allow components in these areas to be designed separately and integrated without interference.

This section describes volumetric zones based from the motherboard planar (referred to as motherboard zones – Section 3.2.1), volumetric zones based from the chassis (referred to as chassis zones – Section 3.2.2), and the placement requirements for all system components with respect to the zones. These requirements ensure that key system components do not mechanically interfere when they are integrated into a system.

Figure 3 shows some of these zones. Zones A, B, C, and D are motherboard zones and Zones F, G, and H are chassis zones. Not shown in this figure are chassis zones J and K (under the motherboard).

Note that some zones, like Zone A and Zone F, have two heights associated with them. This is to accommodate the two types (heights) of thermal modules and the corresponding system designs. Type I (Standard Height) is intended to be utilized where space is available to maximize the volume available for the thermal module solution design, while Type II (Low Profile) is included as an option for designs where lower profile components in this area are highly valued.



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Figure 3. Chassis and Motherboard Volumetric Zones (not all zones are shown)

3.2.1 Motherboard Volumetric Zones

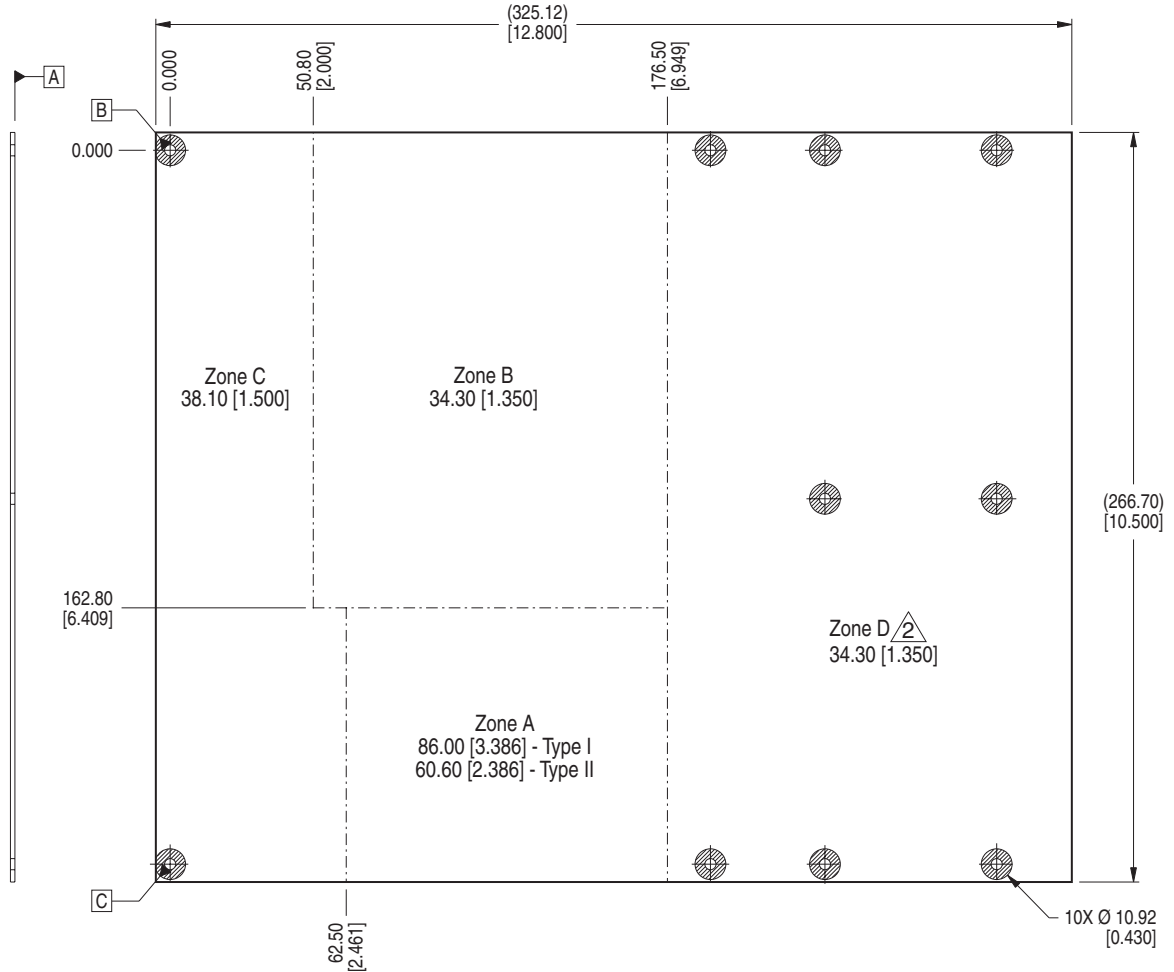
Sections 3.2.1.1 and 3.2.1.2 define the footprint and height constraints that comprise the overall motherboard volumetric zones. All components in a BTX-compatible system must adhere to the motherboard volumetric zones according to the requirements in Table 6.

Table 6. Categories and Requirements for Motherboard Volumetric Zones

| Category | Examples | Requirements |
|-------------------------|--|---|
| Motherboard components | Memory modules, processors, rear panel motherboard connectors and mating cable connectors, component heatsinks, components soldered to motherboard | Must fit completely within the motherboard volumetric zones (primary and secondary side) |
| Chassis components | Chassis walls, chassis pan, motherboard mounting features, peripheral mounting brackets | Must not intersect the motherboard volumetric zone at any point. In addition, adequate clearance should be provided between the chassis, the motherboard volumetric and installed system components to avoid component interference and/or damage during shipping or other dynamic conditions. |
| Transition components | Add-in cards, air ducts, Thermal Module, SRM, cabling from the motherboard to system components, motherboard EMI grounding feature | May cross the outer boundary of the motherboard volumetric zone. Some of these components, such as add-in cards, may have their own mechanical volumetric specifications which should be considered by the designer in addition to those specified in this document. The Thermal Module should not intersect the top boundary of Zones A and C, but will intersect the boundaries adjacent to chassis Zones F and G to extend into these zones. |
| Other System components | Disk drives, front panel cards, system power supply, and other system components not listed above | Must not intersect the motherboard volumetric zone at any point. In addition, should provide adequate clearance between installed system components and the motherboard volumetric zone to avoid component interference and/or damage during shipping or other dynamic conditions. |

3.2.1.1 Motherboard Primary Side Volumetric Zones

Motherboard primary side volumetric zones are defined in Figure 4 . All areas are defined from the top surface of the motherboard.



Notes:

1. No components or traces allowed in the crosshatched areas.
- △ To avoid mechanical interference, motherboard and chassis designers who choose to support add-in cards in zone "D" should observe additional mechanical constraints imposed by the add-in card specifications.

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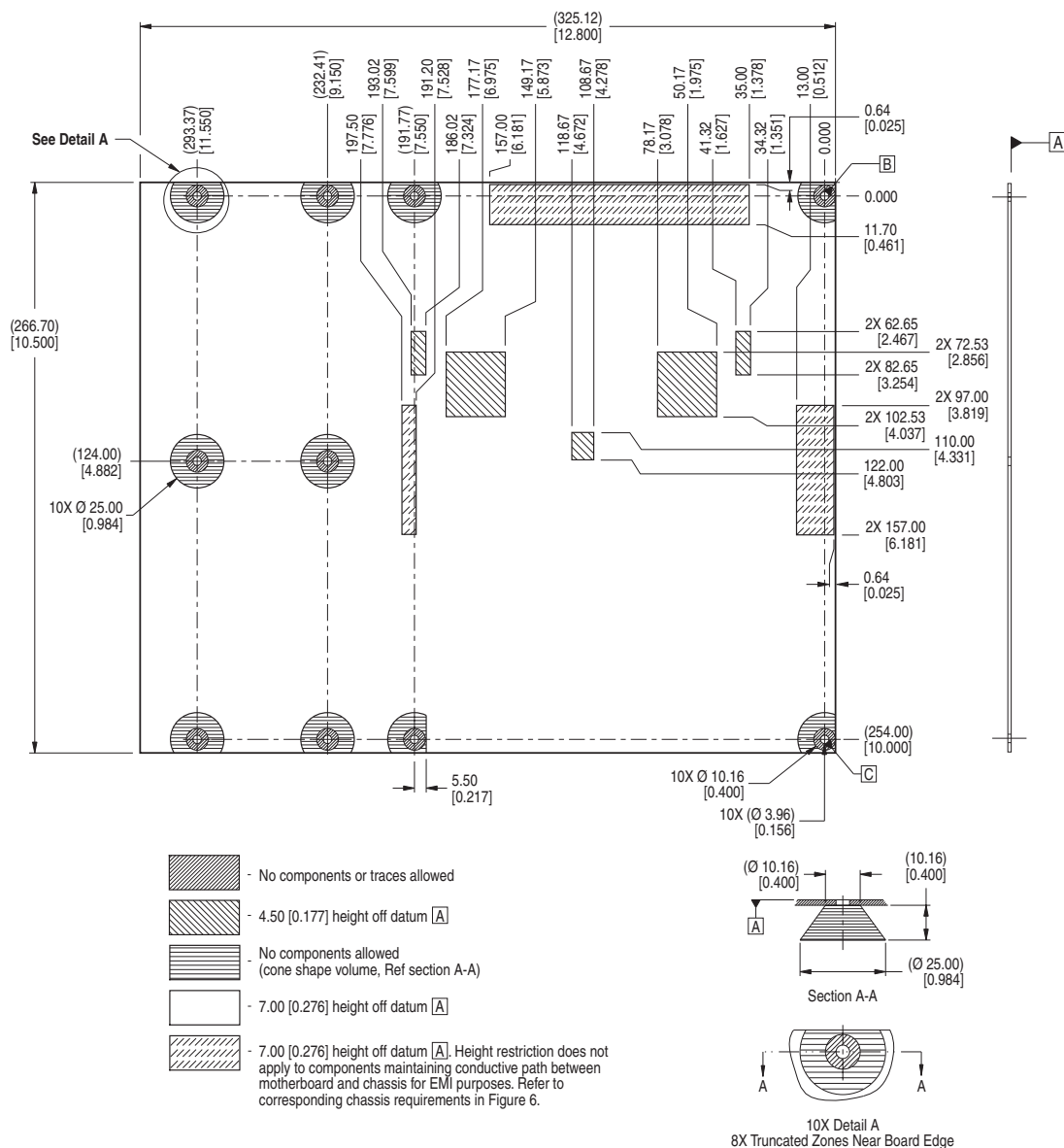
Figure 4. Motherboard Primary Side Volumetric Zone

3.2.1.2 Motherboard Secondary Side Zones

Motherboard secondary side volumetric zones are defined in Figure 5. All areas are defined from the bottom surface of the motherboard.

Also defined in Figure 5 are areas for inclusion of optional EMI features. If needed, EMI grounding features extending from the motherboard to the chassis should only be designed within these areas to ensure contact with the corresponding areas reserved in the chassis below the board for this purpose.

All zone boundaries are defined to avoid interference with components in the assembled condition. Additional clearances based on target assembly processes may need to be incorporated.



OM16301

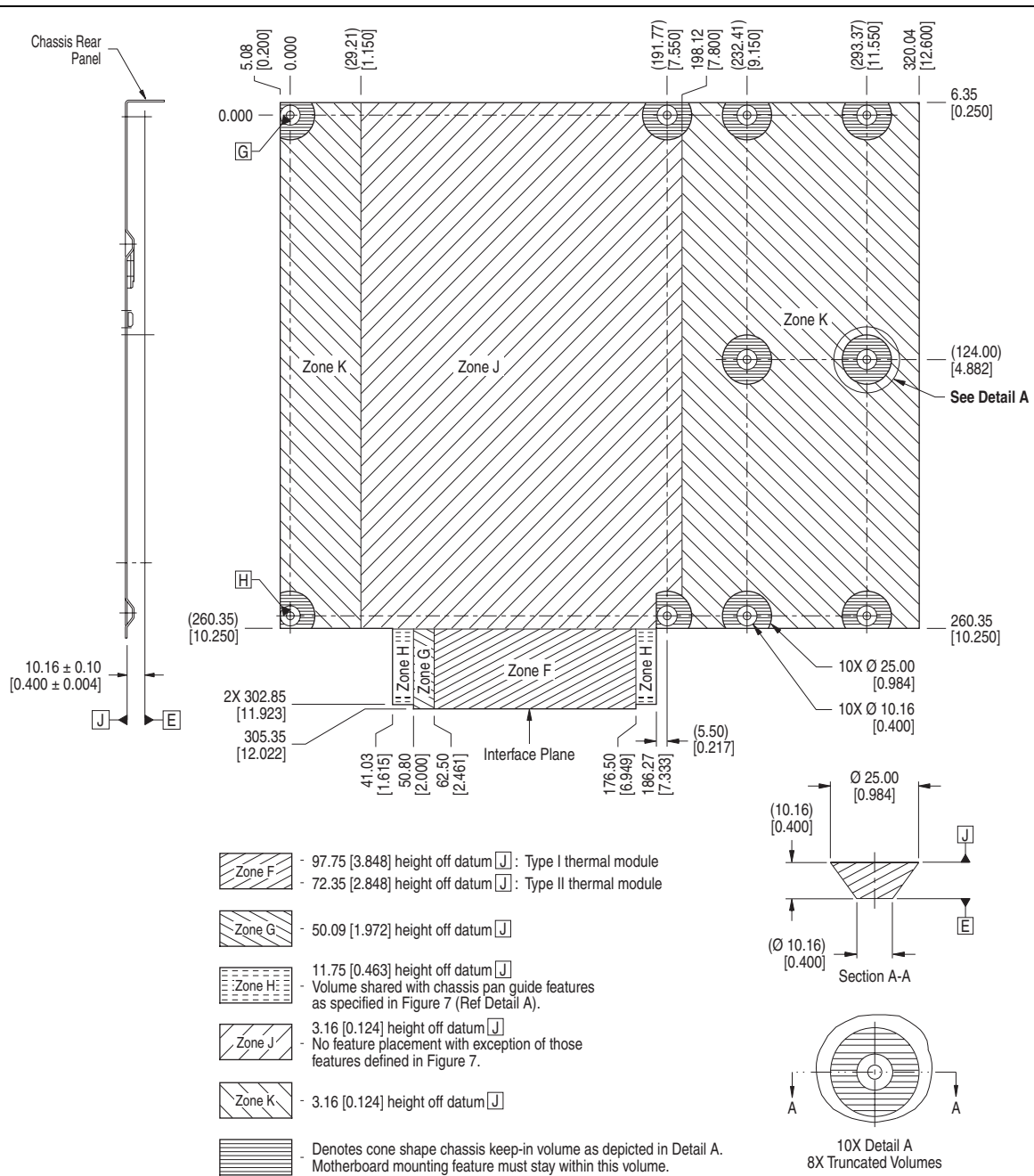
Figure 5. Motherboard Secondary Side Volumetric Zones

3.2.2 Chassis Volumetric Zones

Figure 6 defines the footprint and heights that comprise the *chassis volumetric zones* as referenced from the top surface of the chassis pan. All components in a BTX-compatible system must adhere to the chassis volumetric zones according to the requirements in Table 7. Note that although Figure 6 shows the zones for the widest motherboard (seven slot board), rules for Zone J scale according to the width of the motherboard being used. Requirements in this section do not affect the volume beyond the extensible edge of the motherboard that the system is designed to accommodate.

Table 7. Categories and Requirements for Chassis Zones

| Category | Examples | Requirements |
|-------------------------|--|--|
| Motherboard Components | Memory modules, processors, rear panel motherboard connectors and mating cable connectors, component heatsinks, and components soldered to motherboard | Must not intersect any of the chassis volumetric zones at any point. In addition, adequate clearance should be provided between installed system components and the chassis volumetric to avoid component interference and/or damage during shipping or other dynamic conditions. |
| Chassis Components | Chassis pan, board mounting features, and drive bays | Must not intersect volumetric zones G, H, or F. Chassis features in Zone K must not intersect the upper boundary of Zone K. Only the features called out in Figure 6 and Figure 7 are allowed in Zone J. No other chassis features should intersect this zone. Board mounting features should stay within the zones specified for these features. |
| Transition Components | SRM and Thermal Module | May cross the outer boundary of some chassis zones. Components such as an SRM may have their own requirements which should be considered by the designer in addition to those specified in this document. |
| Other System Components | Disk drives and system power supply | Must not intersect any of the chassis volumetric zones at any point. In addition, adequate clearance should be provided between installed system components and the chassis volumetric to avoid component interference and/or damage during shipping or other dynamic conditions. |



OM16302

Figure 6. Chassis Volumetric Zones

3.3 Chassis Mechanical Interfaces

In addition to the other mechanical requirements in this specification, a BTX chassis should provide the interface features listed in Table 8.

Table 8. Chassis Mechanical Interface Requirements

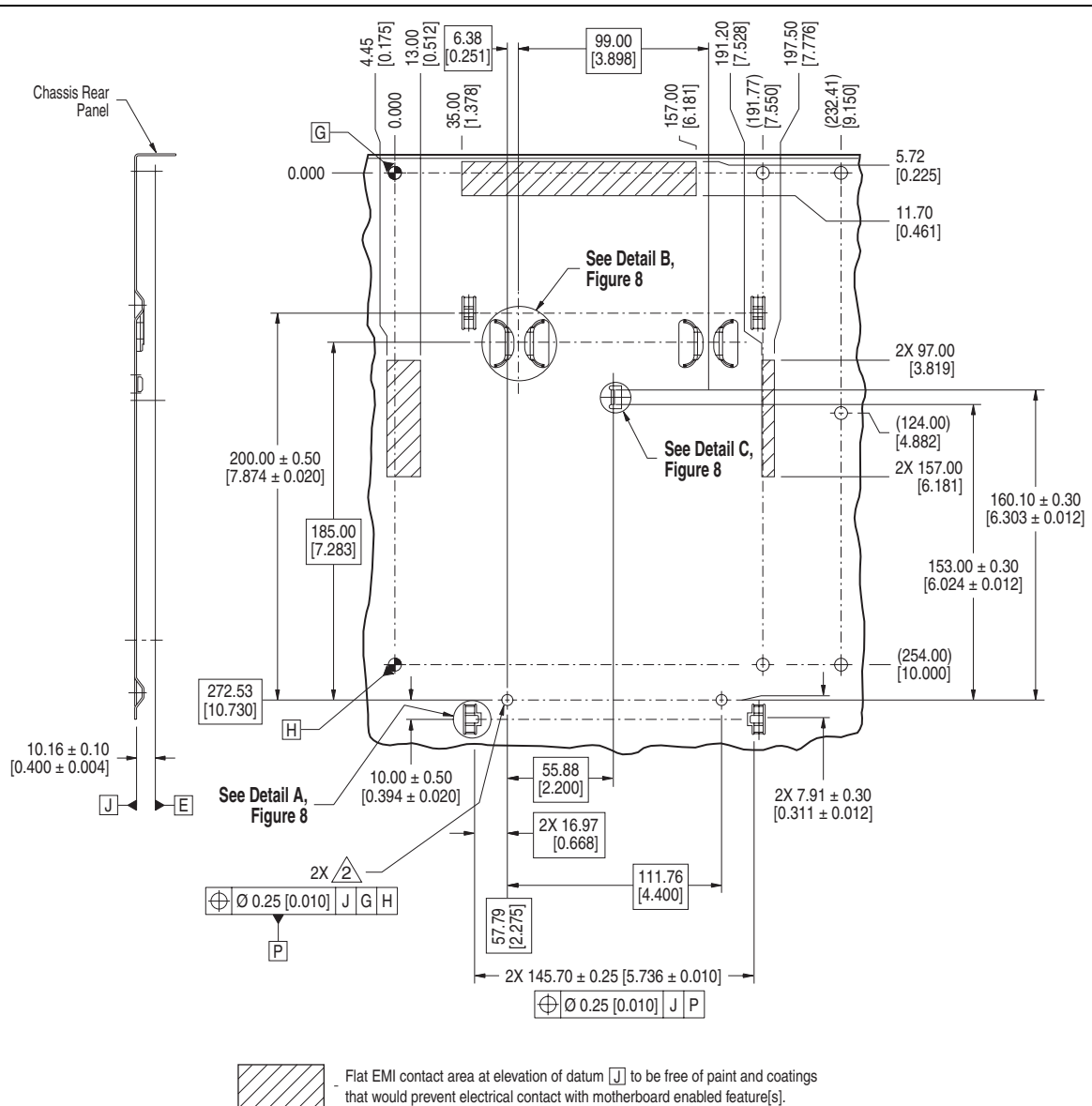
| Mechanical Interface Features | Reference |
|--|--------------------------|
| Areas on the chassis pan for interface with board EMI grounding features | Figure 7 |
| Attach features for a Support and Retention Module (SRM) | Figure 7 and Figure 8. |
| Common interface to a thermal module | Section 3.3.3, Figure 10 |
| Rear panel aperture for interface with the motherboard rear panel connectors | Section 3.3.4, Figure 11 |

3.3.1 Chassis Interface for EMI Grounding

The chassis should allow areas as shown in Figure 7 to interface with the grounding features on the motherboard. These areas must be unpainted and allow conduction to chassis for grounding.

3.3.2 Chassis Interface to Support and Retention Module

A Support and Retention Module, or SRM, is a system component that can be used to support an area of the motherboard and loads upon the motherboard such as a thermal module. An SRM can reside in chassis volumetric zone J and also may share chassis zone K as well as the secondary side motherboard zone. A BTX chassis should include the features shown in Figure 7 to provide a standard interface for SRMs. Accordingly, an SRM for a BTX chassis and motherboard should be designed to fit into and mate with these features. The interface between the SRM and the motherboard will vary depending on the motherboard and thermal module design.

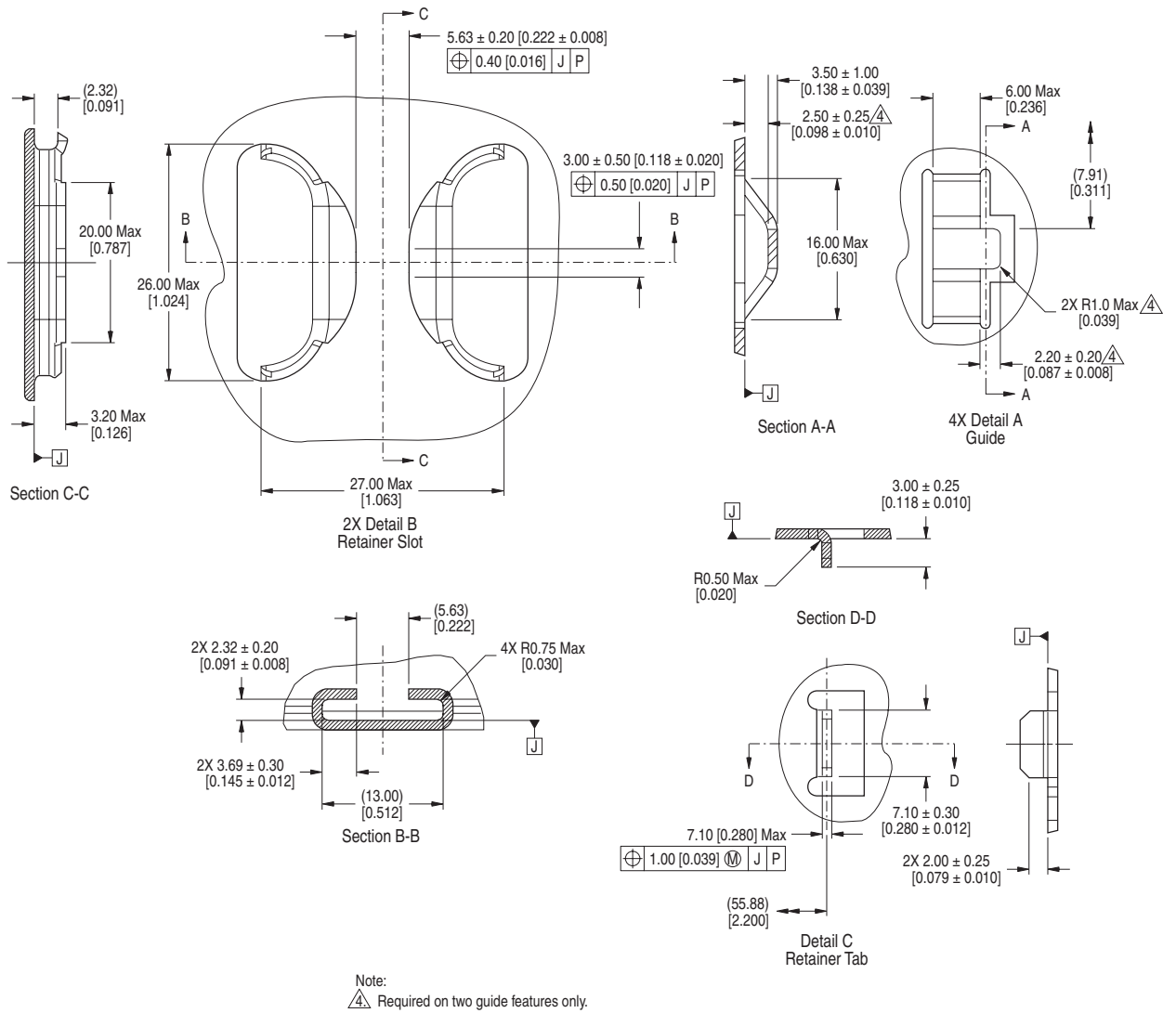


Flat EMI contact area at elevation of datum J to be free of paint and coatings that would prevent electrical contact with motherboard enabled feature[s].

- Notes:
- Chassis datum axes G and H are coincident to motherboard datum axes B and C and simulated by chassis to motherboard fastening features. Chassis datum axis E corresponds to motherboard elevation plane as simulated by chassis fastening features.
 - 6-32 threaded standoff with height of 3.00 ± 0.15 [0.118 ± 0.006] above datum J and Ø 7.11 ± 0.12 [0.280 ± 0.005] required.
 - All critical interface features are dimensioned. All other features shown for reference only.

OM16310

Figure 7. Chassis Interface to SRM Requirements

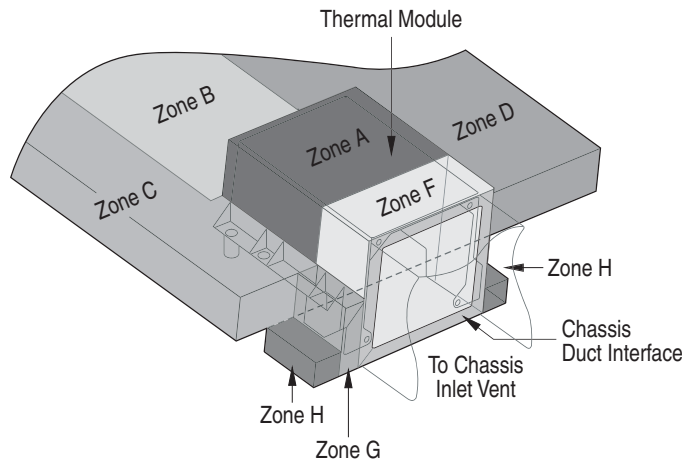


OM16313

Figure 8. Chassis Interface to SRM Requirement Details

3.3.3 Chassis Interface to Thermal Module

In order to provide a standard interface between a thermal module and the chassis, a common physical interface plane and geometry are required. Figure 9 shows the relationship between the motherboard zones (Section 3.2.1), the thermal module, the chassis/thermal module interface, and the chassis zones (Section 3.2.2).

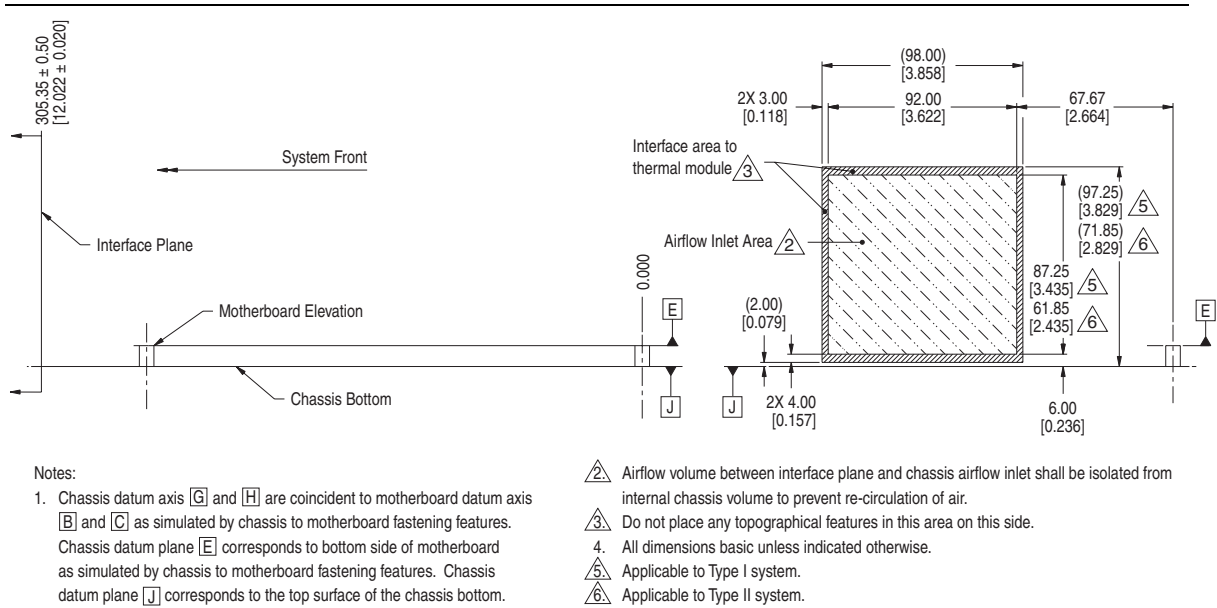


OM16312

Figure 9. Chassis to Thermal Module Interface and Relation to Chassis and Motherboard Zones

Figure 10 defines both a plane relative to the motherboard datums as well as the surface geometry that should be provided on that plane by the chassis (and designed for the thermal module). The surface consists of a frame of minimum width around the window defined for airflow to the thermal module.

The primary purpose for this interface and connection is to provide external air from a vent in the chassis to the thermal module. For this reason, the air channel and the chassis vent should be designed so that there is minimal impedance to airflow from outside the chassis to the defined interface.

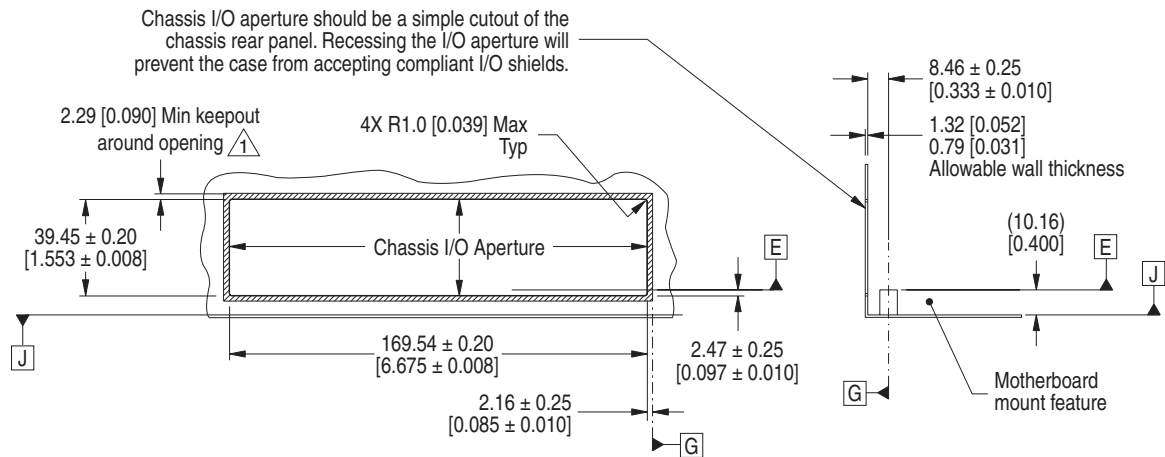


OM16303

Figure 10. Chassis Requirements for Thermal Module Interface Definition

3.3.4 Chassis Rear Panel I/O Interface Requirements

Figure 11 defines the chassis cutout window and associated margins for interface with the rear panel I/O shield.



Notes:

1. \triangle Do not place any topographical features in this area on either the inside or the outside surface of chassis rear panel. Do not paint this area.
2. Datum axis \square G is coincident to datum \square B of motherboard on Figure 11.
3. Chassis datum plane \square E corresponds to bottom side of motherboard as simulated by chassis fastening features. Chassis datum plane \square J corresponds to the top surface of the chassis bottom.

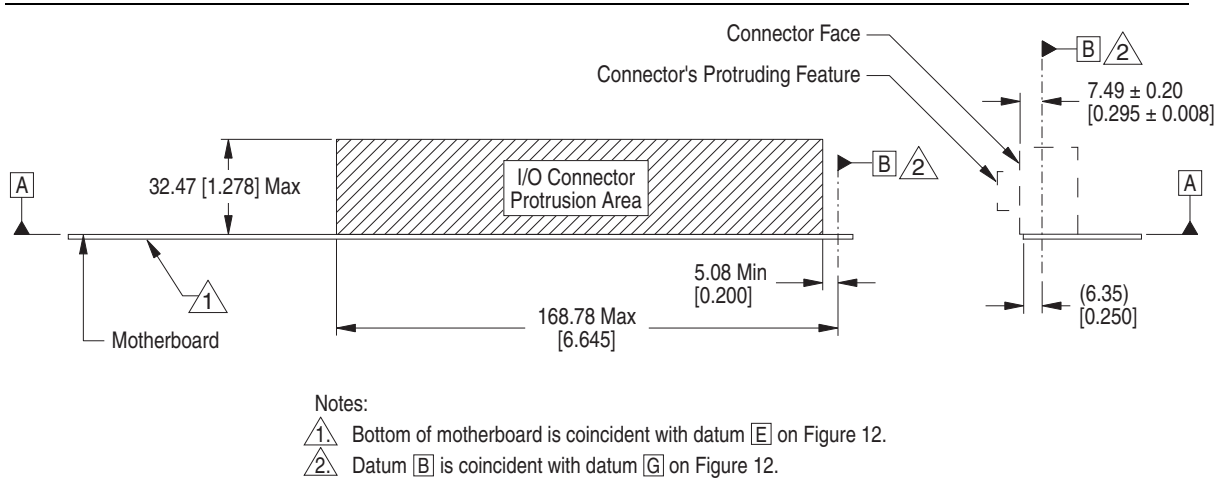
OM16307

Figure 11. Chassis Rear Panel I/O Aperture Requirements

3.4 Motherboard Mechanical Interfaces

3.4.1 Motherboard Rear Panel Interface Requirements

All rear panel external motherboard connectors (and their mating cable connectors) must pass through the motherboard rear panel I/O shield within the shaded window depicted in Figure 12.



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Figure 12. Motherboard Rear Panel I/O Aperture Requirements

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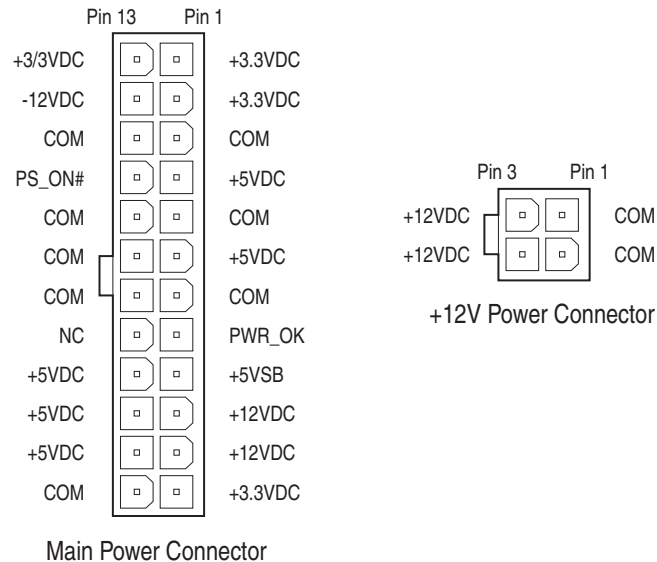
4. Electrical Interface Requirements

4.1 Motherboard Power Supply Connectors

Figure 13 defines the required pinout for the required connectors listed in Table 9. The connectors provide a standard interface between a BTX motherboard and a compatible system power supply. Further information on critical signals is defined in Section 4.2. For additional information on the design of compatible system power supplies, refer to the design guides at the location listed in Section 5.

Table 9. Power Supply Connectors

| Connector Description | Status | Board-mounted Header | Mating Power Supply Receptacle | Electrical Signal Implementation |
|-----------------------|------------------------------|---------------------------------|---------------------------------|----------------------------------|
| Main Power Connector | Required on all motherboards | Molex† 44206-0007 or equivalent | Molex† 39-01-2240 or equivalent | Per Figure 13 and Section 4.2 |
| +12V Power Connector | Required on all motherboards | Molex† 39-29-9042 or equivalent | Molex† 39-01-2040 or equivalent | Per Figure 13 and Section 4.2 |



OM16308

Figure 13. Power Supply Connectors

4.2 Motherboard Power and Control Signal Definitions

4.2.1 +5VSB

+5VSB is a standby voltage supply that is active whenever AC power is present to the system power supply. It provides a power source for circuits that must remain operational when the three main DC outputs (+12VDC, +5VDC, +3.3VDC) are in a disabled state. Example uses include soft power control, Wake on LAN technology, wake-on-modem, intrusion detection, or suspend (sleep) state activities. The maximum current available from the +5VSB output depends on the design of the system power supply.

4.2.2 PS_ON#

PS_ON# is an active low, TTL-compatible signal that allows the motherboard to enable the three main system power supply DC output rails (+3.3VDC, +5VDC, +12VDC). PS_ON# is pulled up to +5VSB via a 10 k Ω resistor internal to the system power supply.

When PS_ON# is pulled to TTL low, the DC outputs are enabled by the system power supply.

When PS_ON# is held to TTL high by the motherboard or left open circuited, the system power supply shall not deliver current at the main DC outputs and shall hold them at zero potential with respect to ground.

Table 10. PS_ON# Signal Characteristics

| | Min. | Max. |
|--|-------------|-------------|
| V _{IL} , Input Low Voltage | 0.1 V | 0.8 V |
| I _{IL} , Input Low Current, V _{in} = 0.4 V | | -1.6 mA |
| V _{IH} , Input High Voltage, I _{in} = -200 μ A | 2.0 V | |
| V _{IH} open circuit, I _{in} = 0 | | 5.25 V |

4.2.3 PWR_OK

PWR_OK is a power good signal asserted by the system power supply to indicate that the +5VDC, +3.3VDC, and +12VDC outputs are above the undervoltage thresholds of the power supply. When this signal is asserted high, the system power supply has sufficient energy stored by the converter to guarantee continuous power operation for a minimum hold-up time per the system power supply's specification. Conversely, when one or more of the output voltages fall below their undervoltage threshold, or when mains power has been removed for a time sufficiently long so that power supply operation is no longer guaranteed beyond the hold up time, PWR_OK will be de-asserted to a low state by the power supply.

Table 11. PWR_OK Signal Characteristics

| Parameter | Value |
|--------------------------------|---|
| Signal type | +5 V TTL compatible |
| Logic level low | < 0.4 V while sinking 4 mA |
| Logic level high | Between 2.4 V and 5 V output while sourcing 200 μ A |
| High-state output impedance | 1 k Ω from output to common |
| PWR_OK delay | 100 ms < T_3 < 500 ms |
| PWR_OK rise time | $T_4 \leq 10$ ms |
| AC loss to PWR_OK hold-up time | $T_5 \geq 16$ ms |
| Power-down warning | $T_6 \geq 1$ ms |

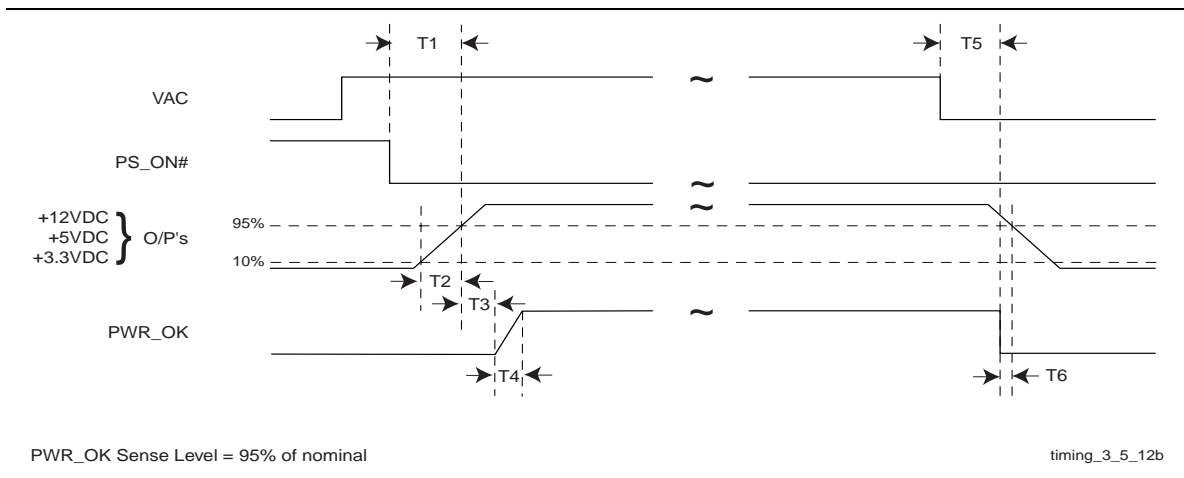


Figure 14. Power Timing

4.2.4 Voltage Tolerances

The system power supply shall guarantee that the tolerances for the main DC outputs comply with the values listed in Table 12, subject to the limits of the system power supply's specified capabilities.

Table 12. DC Output Voltage Tolerances

| Voltage Rail | Tolerance |
|--------------|------------|
| +3.3VDC | $\pm 5\%$ |
| +5VDC | $\pm 5\%$ |
| +12VDC | $\pm 5\%$ |
| -12VDC | $\pm 10\%$ |
| +5VSB | $\pm 5\%$ |

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5. Additional Information

For additional information beyond the requirements of this specification, refer to:

<http://www.formfactors.org>

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